Supplementary Materials: Comparison of Ultrasonic Welding and Thermal Bonding for the Integration of Thin Film Metal Electrodes in Injection Molded Polymeric Lab-on-Chip Systems for Electrochemistry

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Figure S1. Representative data for (a) electrical cyclic voltammetry (CV) and (b) electrochemical impedance spectroscopic (EIS) characterization of Au electrodes in a chip thermally bonded at T = 125 °C, F = 1 kN, t = 10 min.